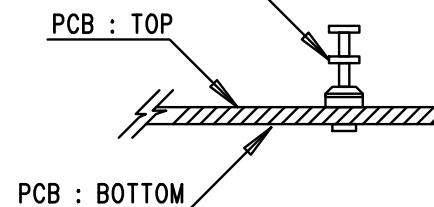


## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. TURRETS : MILL-MAX 2501-2



TITLE: TOP ASSEMBLY DRAWING  
NO-OPTO ISOLATED FLYBACK CONVERTER

SIZE N/A	IC NO. LT3001ES5 DC3006A	REV. 1
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FILENAME: DC3006A-1.PCB	SHT 1 OF 2
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